

PART INFORMATION

Mfg Item Number	FXTH870511DT1
Mfg Item Name	QFN-EP MAP 24 7*7*2.2 P1

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2018-05-15
Response Document ID	00CAK50001S539A1.12
Contact Name	Freescale Semiconductor Inc
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DECLARATION

EU RoHS	Yes
Pb Free	No
HalogenFree	Yes
Plating Indicator	e4
EU RoHS Exemption(s)	7c-l

MANUFACTURING

Mfg Item Number	FXTH870511DT1
Mfg Item Name	QFN-EP MAP 24 7*7*2.2 P1
Version	ALL
Weight	0.306300
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Bonding Wire	0.00025						g				
Bonding Wire		Metals	Gold, metal	7440-57-5		0.00025	g	1000000	100	816	0.0816
Non-conductive Epoxy	0.0003						g				
Non-conductive Epoxy		Plastics/polymers	Poly[o-cresyl glycidyl ether]-co-formaldehyde	20690-82-2		0.00003	g	100000	10	97	0.0097
Non-conductive Epoxy		Plastics/polymers	4,4'-isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate	25068-38-6		0.000075	g	250000	25	244	0.0244
Non-conductive Epoxy		Plastics/polymers	Phenol p-xylylene dimethyl ether copolymer	20834-02-6		0.00009	g	300000	30	293	0.0293
Non-conductive Epoxy		Glass	Silicon dioxide	7631-86-9		0.000075	g	250000	25	244	0.0244
Non-conductive Epoxy		Plastics/polymers	Acrylic acid ester copolymer	78506-70-4		0.00003	g	100000	10	97	0.0097
Gel Die Encapsulant	0.0067						g				
Gel Die Encapsulant		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	69083-19-2		0.0066642	g	994988	99.4988	21764	2.1764
Gel Die Encapsulant		Solvents, additives, and other materials	Ethylbenzene	100-41-4		0.0000358	g	5012	0.5012	109	0.0109
Bonding Wire	0.00025						g				
Bonding Wire		Metals	Gold, metal	7440-57-5		0.00025	g	1000000	100	816	0.0816
Epoxy Die Attach	0.0001						g				
Epoxy Die Attach		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	69083-19-2		0.00006	g	600000	60	195	0.0195
Epoxy Die Attach		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.00003	g	300000	30	97	0.0097
Epoxy Die Attach		Solvents, additives, and other materials	Dimethyl methyl hydrogen siloxane	68037-69-2		0.0000091	g	91000	9.1	29	0.0029
Epoxy Die Attach		Metals	Other platinum compounds	-		0.0000009	g	9000	0.9	2	0.0002
Bonding Agent	0.0025						g				
Bonding Agent		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	69083-19-2		0.0015	g	600000	60	4907	0.4907
Bonding Agent		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.00075	g	300000	30	2448	0.2448
Bonding Agent		Solvents, additives, and other materials	Dimethyl methyl hydrogen siloxane	68037-69-2		0.0002275	g	91000	9.1	742	0.0742
Bonding Agent		Metals	Other platinum compounds	-		0.0000225	g	9000	0.9	73	0.0073
Die Encapsulant, Halogen-free	0.1993						g				
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.000967	g	5001	0.5001	3253	0.3253
Die Encapsulant, Halogen-free		Plastics/polymers	Phenolic Resin	125133-38-2		0.0049835	g	25005	2.5005	16269	1.6269
Die Encapsulant, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.01495049	g	75015	7.5015	48809	4.8809
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0		0.16341882	g	819964	81.9964	533557	53.3557
Die Encapsulant, Halogen-free		Plastics/polymers	Epoxy Resin	115254-47-2		0.01495049	g	75015	7.5015	48809	4.8809
Copper Lead Frame	0.0072						g				
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.00698241	g	969780	96.978	22795	2.2795
Copper Lead Frame		Metals	Gold, metal	7440-57-5		0.0000137	g	190	0.019	4	0.0004
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.0000204	g	284	0.0284	6	0.0006
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.00015373	g	21351	2.1351	501	0.0501
Copper Lead Frame		Lead/Lead Compounds	Lead	7439-92-1		0.00000007	g	10	0.001	0	0
Copper Lead Frame		Nickel (external applications only)	Nickel	7440-02-0		0.00005728	g	7955	0.7955	187	0.0187
Copper Lead Frame		Metals	Palladium, metal	7440-05-3		0.0000018	g	250	0.025	5	0.0005
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0.0000013	g	180	0.018	4	0.0004
Non-Conductive Epoxy/Adhesive	0.0001						g				
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Polytetrafluoroethylene	9002-84-0		0.000045	g	450000	45	146	0.0146
Non-Conductive Epoxy/Adhesive		Glass	Silicon dioxide	7631-86-9		0.000003	g	30000	3	9	0.0009
Non-Conductive Epoxy/Adhesive		Metals	Titanium (IV) Oxide	13463-67-7		0.000007	g	70000	7	22	0.0022
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000005	g	50000	5	16	0.0016
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Proprietary Material-Other Bismaleimides	-		0.00002	g	200000	20	65	0.0065
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other non-halogenated polymers	-		0.00002	g	200000	20	65	0.0065
Encapsulant Gel	0.0067						g				
Encapsulant Gel		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	69083-19-2		0.0066642	g	994988	99.4988	21764	2.1764
Encapsulant Gel		Solvents, additives, and other materials	Ethylbenzene	100-41-4		0.0000358	g	5012	0.5012	109	0.0109
Silicon Semiconductor Die	0.00535						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000107	g	20000	2	349	0.0349
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.005243	g	980000	98	17117	1.7117
Lid	0.0696						g				
Lid		Metals	Chromium, metal	7440-47-3		0.01262412	g	181381	18.1381	41214	4.1214
Lid		Solvents, additives, and other materials	Sulfur	7704-34-9		0.0000209	g	30	0.003	6	0.0006
Lid		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00002645	g	2995	0.2995	680	0.068
Lid		Silicon	Silicon	7440-21-0		0.00043771	g	6289	0.6289	1429	0.1429
Lid		Metals	Iron, metal	7439-89-6		0.04957434	g	712275	71.2275	161848	16.1848
Lid		Metals	Manganese, metal	7439-96-5		0.00072955	g	10482	1.0482	2381	0.2381
Lid		Nickel (external applications only)	Nickel	7440-02-0		0.00598901	g	86049	8.6049	19552	1.9552
Lid		Solvents, additives, and other materials	Carbon	7440-44-0		0.00003473	g	499	0.0499	113	0.0113
Pb Glass Frit Semiconductor Di	0.0026				7c-1		g				
Pb Glass Frit Semiconductor Di		Lead/Lead Compounds	Lead (II) stannate	12060-00-3		0.00002699	g	10381	1.0381	88	0.0088
Pb Glass Frit Semiconductor Di		Glass	Fibrous-glass-wool	65997-17-3		0.00002585	g	9943	0.9943	84	0.0084
Pb Glass Frit Semiconductor Di		Solvents, additives, and other materials	2,2,4-trimethyl-1,3-pentanediol-1-monoisobutyrate	25265-77-4		0.00002585	g	9943	0.9943	84	0.0084
Pb Glass Frit Semiconductor Di		Glass	Silicon, doped	-		0.00252131	g	969733	96.9733	8231	0.8231
Silicon Semiconductor Die	0.00535						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000107	g	20000	2	349	0.0349
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.005243	g	980000	98	17117	1.7117

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/FXTH870511DT1_IPC1752_v11.xml

http://www.freescale.com/mcdfs/FXTH870511DT1_IPC1752A.xml